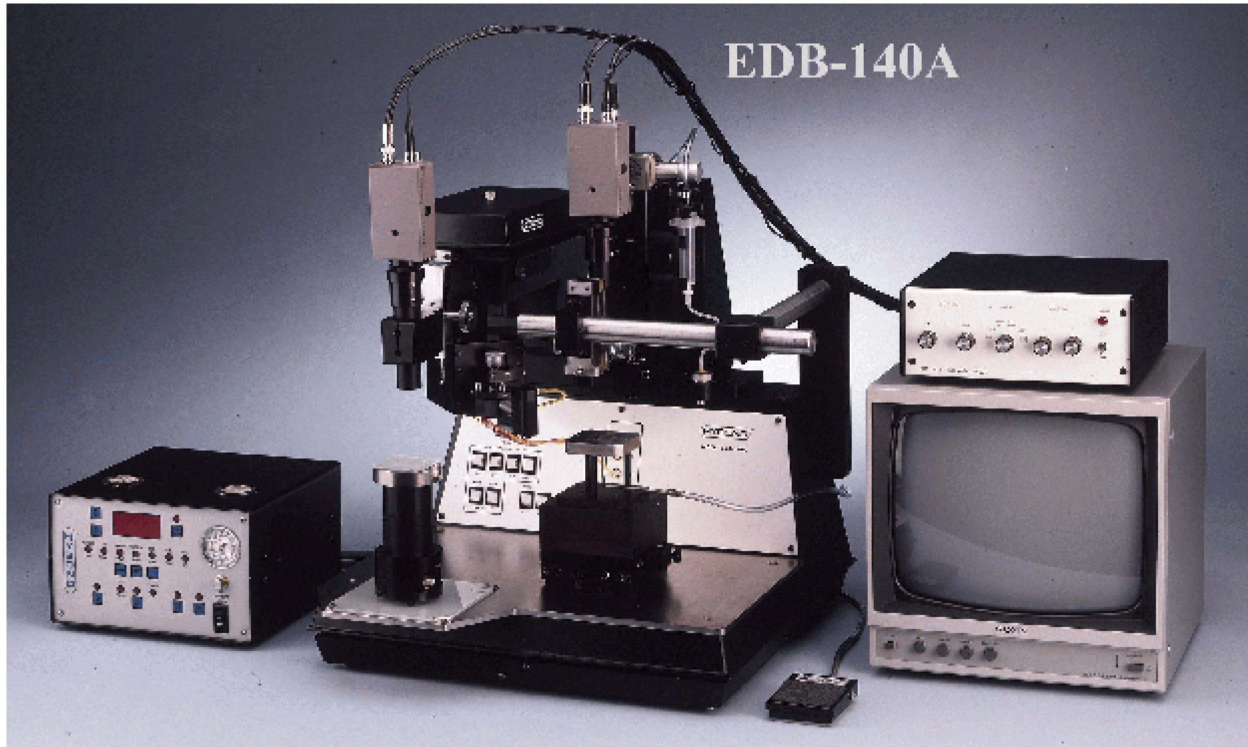
HYBOND

MODEL EDB-140A

EPOXY/SILVER GLASS DIE BONDER



STANDARD FEATURES:

- Black & white CCTV system (as shown).
- Package depth sensor for consistent and precise bond line thickness.
- Programmable dispense control unit.
- Storage for up to 99 dispense programs.
- Manual X-Y alignment stage.
- Waffle pack/loose die pick up pedestal.
- Pitch and roll adjustments for bond head.
- Custom dispense heads/dispense patterns.
- Custom die collets to match customer die.
- Manual and semiautomatic operation modes.
- PLC control.

HYBOND's Model EDB-140A is a semiautomatic epoxy/silver glass die bonder which provides uniform epoxy or silver glass dispensing with consistent material thickness and precise die placement. The EDB-140A can be fitted with a waffle pack/jel pack or loose die pedestal or a die ejector for holding die on wafers. The dispense system can be fitted with Hybond's micro-dispense head for extremely low volume epoxy dispensing. This die bonder is rugged enough for continuous production and ideal for small production runs and laboratory applications. Die pick up and placement are made easy with the aid of dual CCTV cameras and a split screen monitor which incorporates a die and package visual targeting system. The EDB-140A is modular and easily adapts to modifications to accommodate fixturing for custom packages.

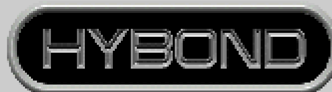
Partial List Of Available Options:

- Die ejector systems.
- Color CCTV system.
- Zoom stereo microscope with swivel base.
- Dual fiberoptic illumination system.
- Stir column for silver glass/conductive epoxy.
- Micro-dispensing head and control box.
- Lead frame indexing systems.
- Semi-automatic indexing systems.
- Remote pendant controls.
- Customization based on specific application.

EDB-140A Specifications:

- Dispense System: Programmable, positive pressure system (standard).
- Bond Line Accuracy: ±0.5 mil (±12,7Fm).
- Bond Time Range: 7 to 15 Sec.
- Bond Force Range: 15gr. to 50gr. (standard).
- Temperature Control Range: Ambient.
- Bondable Die Size Range: 6x6 mils (152x152Fm) to 750x750 mils (1,9x1,9cm) Standard.
- Placement Accuracy: ±1 mil (25,4Fm) Standard. Less when adding other options.
- Dispense Materials: Epoxy, conductive epoxy and silver glass.
- Bond Head Movement: Motorized, rotational with fixed pickup and placement points.
- Bond Actuation: By opto-switch at fixed height. Cycle initiated by footswitch.
- Z Travel/Vertical Bonding Window: 0.5in. (1,20cm)/0.125 to 0.500in. (0,31 to 1,20cm).
- Table Motion: Manual, with thumbscrews, standard.
- Input Power Requirements: 120 VAC 50/60 Hz @ 8A.
- Minimum Bench Space Required: Height/width: 24in. (45cm) Depth: 22in. (56cm) (Bonder only).
- Facilities Required (minimum): **Vacuum:** 23inHg. **Air:** 60psi
- Unit Weight/Shipping Weight: 75lbs. (34Kg)/150lbs (68Kg). Shipping weight will vary.
- Approximate Units Per Hour (UPH): 90 - 240 depending on options, settings and mode of operation.

For more information contact us:



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